## The Logic to Keep TPOa

Ali Ghiasi – Ghiasi Quantum

IEEE 802.3ck Taskforce Meeting

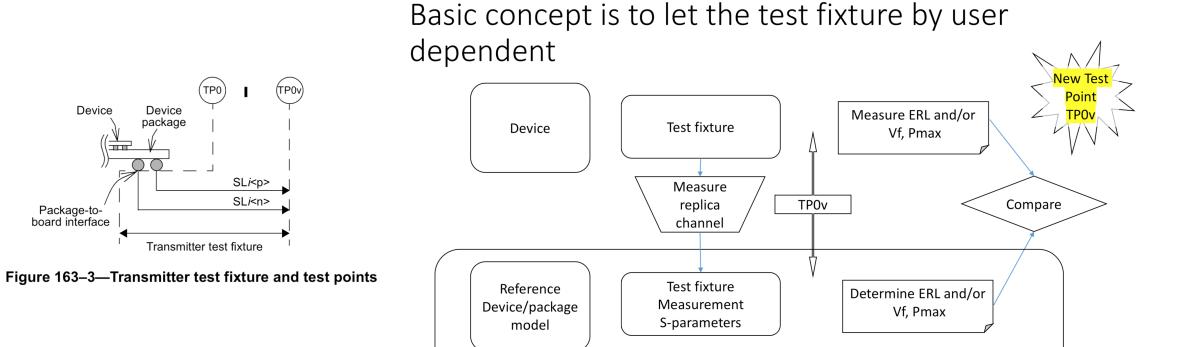
October 14, 2020

# Overview

- Virtual TP0v test point
- Virtual computation method
- **Current vs proposed test fixture loss**
- **Typical high end PCB loss**
- Use of multi-coax for DUT board
- **Summary.**

# TPOv Was Introduced in D1.3

See proposal from Liav and Mellitz <u>mellitz\_3ck\_adhoc\_02\_061020</u>

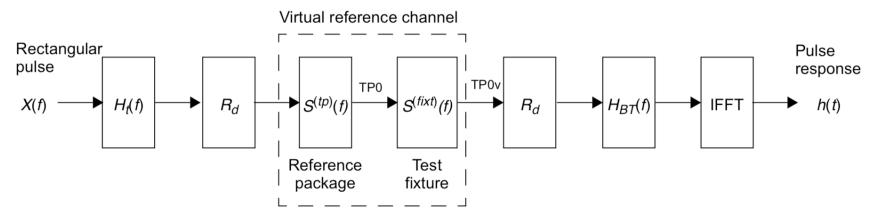


Simulation

# Method to Compute TPOv

### **TPOv** is computed for longest package trace cascaded with test fixture

- Simulated value of Vf, ERL, and Vpeaks are compared with measured parameters
  - The difference between simulated and measured parameters are the normative delta limits
- The normative specifications are dERL, dV, and dVpeak.



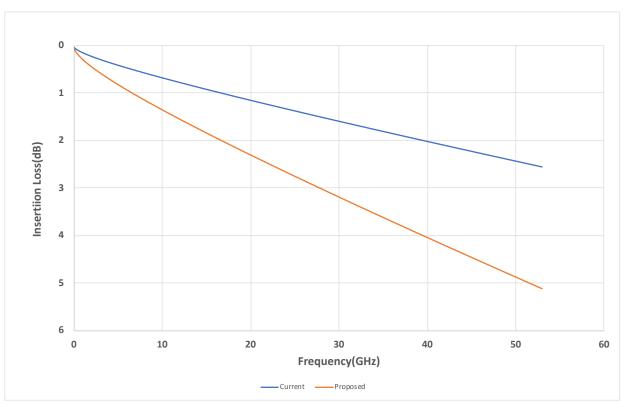
NOTE—The transmitter reference package uses the maximum length specified by the referring subclause.

# Figure 163A–2—Configuration for transmitter reference steady-state voltage, pulse peak and ERL

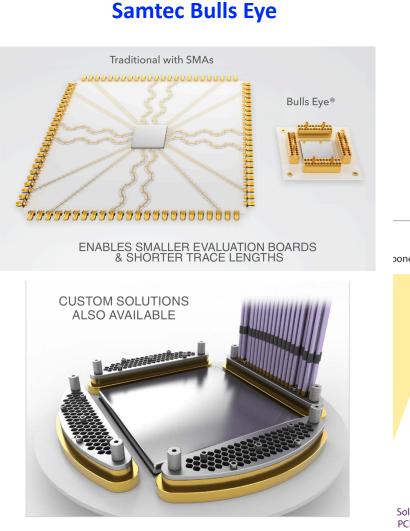
## **Current and Purposed Test Fixture Loss**

Recommend doubling the nominal loss from 1.4 dB to 2.8 dB 163.9.2.2 and use it also for transmit test fixture 163.9.2.1.1

- Proposed TX and RX test fixture loss=0.074+0.2104xsqrt(f)+0.0674xf
- Mated test fixture MCB and HCB their respective losses were also increased to allow reasonable construction



## Example of High-Density Multi-Coax with 70 GHz BW



#### **Ardent Terminator**

#### PATENTED TRISE2254 TERMINATE-R Straight Mount 16x2 70 GHz conential cost High quality .047" durable connectors braided steel (SMA, 2.92 mm, coax cables 1.85 mm) Compression mounts Strain relie to PCB quickly and easily Patented field replaceable interface • Multiple high speed signals in dense 2.54 mm footprint Solderless footprint on PCB eliminates wasted components

#### Huber+Shuner MXPM70

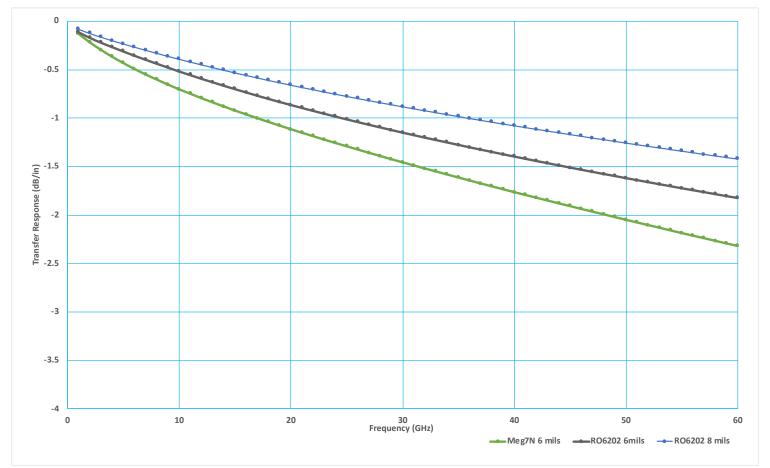




# Typical High-End PCB Losses

### **PCB** losses for Megtron 7N (6 mils trace) and Rogers 6202 (6 and 8 mils traces)

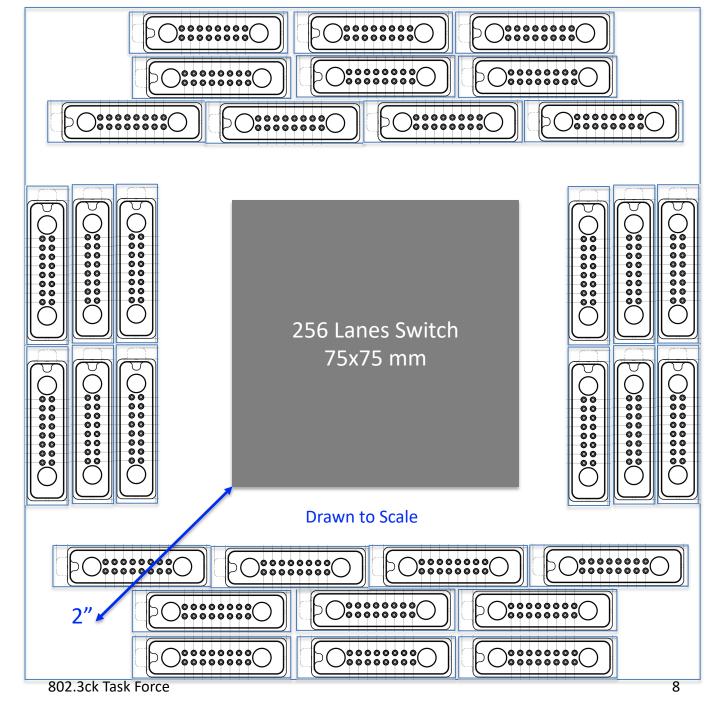
It reasonable to assume high quality test board will have a construction with loss in 0.8-1.0 dB/in at 26.5
More conventional glass weave material such as TUC 933 and 943 have similar DF to RO6202.



# Example 256 Lanes Switch Test Board

## Can one breakout 256 lane switch with just 2"?

- Uses 32 2x8 multi-coax connectors on on top of the board and 32 on the bottom side
- Alternatively one could use 2x16 multicoax or custom multi-coax offered by some of the suppliers
- One could also breakout out 512 lanes switch if needed using custom multicoax connectors using both side of the board.



# **Summary**

### As illustrated multi-coax offer the required density and 70 GHz BW for direct implementation of TP0a

- Similar to MCB/HCB loss TP0a channel loss should be increased
- Recommend to increased TPOa channel loss from 1.4 dB to 2.8 dB which allow 2-3" long PCB trace
- TPOv virtual test point rely on cascaded package model vs an actual DUT board that likely will be using the same multi-coax construction
  - Cascading DUT channel with reference IEEE package may result in unintended spurious response
  - It is assumed that ERL will improve with increased trace loss and Vf/Vpeak degrades where dERL, dVf, and dVpeak are introduced
  - There has not been any measured vs simulated verification of test method given the frequency
  - The dERL, dVf, and dVpeak may not be fully linear with increase or decrease of test board loss
- Use of virtual test point TP5v will be significantly even more challenging
- **TP0a/TP5a** are implementable by increasing loss to 2.8 dB and provides reliable direct measurement
- □ TP0v method with further study and if proven reliable can be an informative method to account when test fixture loss deviate >+/- 0.4 dB from 2.8 dB
  - But normative parameters should be based on 2.8 dB.